TOSHIBA

Date : November 25, 2022

Specification number : H22294307

SPECIFICATION

Product number : TLP185(GB-TPL,SE(T

This specification is approved and confirmed by both

ELECTRONICS SOURCE CO., LTD.

and TOSHIBA ELECTRONIC DEVICES & STORAGE CORPORATION.

ELECTRONICS SOURCE CO., LTD.

TOSHIBA ELECTRONIC DEVICES & STORAGE CORPORATION

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Semiconductor Quality Promotion Dept.

Semiconductor Quality Center

Photocouplers Infrared LED & Photo Transistor

TLP185(SE

1. Applications

- · Office Equipment
- · Programmable Logic Controllers (PLCs)
- · AC Adapters
- · I/O Interface Boards

2. General

The TLP185(SE consist of a photo transistor optically coupled to an infrared LED.

The TLP185(SE photocoupler is housed in the very small and thin SO6 package.

Since TLP185(SE is smaller than DIP package, it's suitable for high-density surface mounting application such as programmable controllers.

3. Features

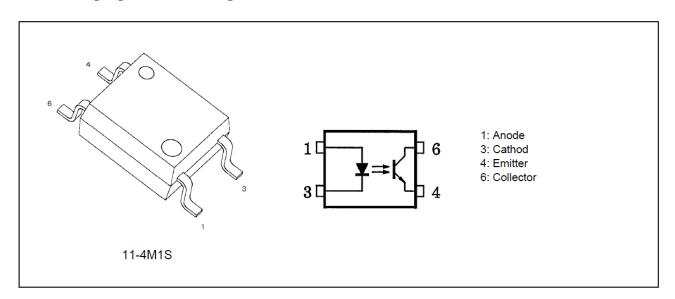
- (1) Collector-emitter voltage: 80 V (min)
- (2) Current transfer ratio
 - GB Rank: 100% (min)
- (3) Isolation voltage: 3750 Vrms (min)
- (4) Operating temperature: -55 to 110 °C
- (5) Safety standards
 - UL-recognized: UL1577, File No.E67349
 - cUL-recognized: CSA Component Acceptance Service No.5A File No.E67349
 - VDE-approved: EN 60747-5-5, EN 62368-1 (**Note 1**) CQC-approved: GB4943.1, GB8898 Thailand Factory



仅适用干海拔 2000m 以下地区安全使用

Note 1: When a VDE approved type is needed, please designate the Option (V4).

4. Packaging and Pin Assignment



Start of commercial production 2013-01



5. Principle of Operation

5.1. Mechanical Parameters

Characteristics	Min	Unit
Creepage distances	5.0	mm
Clearance	5.0	
Internal isolation thickness	0.4	

6. Absolute Maximum Ratings (Note) (Unless otherwise specified, Ta = 25 °C)

	Characteristics	Symbol	Note	Rating	Unit
	Input forward current	l _F		50	mA
	Input forward current derating (T _a ≥ 90 °C)	ΔI _F /ΔTa		-1.5	mA/°C
	Input forward current (pulsed)	I _{FP}	(Note 1)	1	Α
LED	Input reverse voltage	V_R		5	V
	Input power dissipation	P _D		100	mW
	Input power dissipation derating $(T_a \ge 90 \text{ °C})$	$\Delta P_D/\Delta T_a$		-2.86	mW/°C
	Junction temperature	Tj		125	°C
	Collector-emitter voltage	V_{CEO}		80	V
	Emitter-collector voltage	V _{ECO}		7	V
Detector	Collector current	Ic		50	mA
Detector	Collector power dissipation	Pc		150	mW
	Collector power dissipation derating (T _a ≥ 25 °C)	$\Delta P_C/\Delta T_a$		-1.5	mW/°C
	Junction temperature	Tj		125	
	Operating temperature	T _{opr}		-55 to 110	°C
	Storage temperature	T _{stg}		-55 to 125	C
Common	Lead soldering temperature (10 s)	T _{sol}		260	
	Total power dissipation	P _T		200	mW
	Isolation voltage AC, 60 s, R.H. ≤ 60 %	BVs	(Note 2)	3750	Vrms

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: Pulse width (PW) ≤ 100 µs, f = 100 Hz

Note 2: This device is considered as a two-terminal device: Pins 1 and 3 are shorted together, and pins 4 and 6 are shorted together.

7. Electrical Characteristics (Unless otherwise specified, Ta = 25 °C)

	Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit	
	Input forward voltage	VF	I _F = 10 mA	1.1	1.25	1.4	V	
LED	Input reverse current	I _R	V _R = 5 V	-	_	5	μΑ	
	Input capacitance	Ct	V = 0 V, f = 1 MHz	-	30	-	рF	
	Collector-emitter breakdown voltage	$V_{(BR)CEO}$	I _C = 0.5 mA	80	-	-	V	
	Emitter-collector breakdown voltage	V _{(BR)ECO}	I _E = 0.1 mA	7	-	-	>	
Detector	Deads Comment	I _{DARK}	V _{CE} = 48 V	-	0.01	0.08	μA	
	Dark Current		V _{CE} = 48 V, T _a = 85 °C	-	2	50		
	Collector-emitter capacitance	C_CE	V = 0 V, f = 1 MHz	-	10	-	pF	



8. Coupled Electrical Characteristics (Unless otherwise specified, Ta = 25 °C)

Characteristics	Symbol	Note	Test Condition	Min	Тур.	Max	Unit
Current transfer ratio	Ic / I _F	(Note 1)	I _F = 5 mA, V _{CE} = 5 V	100	-	600	%
Saturated current transfer ratio	I _C / I _{F(sat)}		I _F = 1 mA, V _{CE} = 0.4 V	30	-	-	70
Collector-emitter saturation	.,		I _F = 8 mA, I _C =2.4 mA	-	-	0.3	
voltage	V _{CE(sat)}		I _F = 1 mA, I _C =0.2 mA	-	-	0.3	V
OFF-state collector current	I _{C(off)}		V _F = 0.7 V, V _{CE} = 48 V	-	1	10	μA

Note 1: See Table 8.1 for current transfer ratio.

Table 8.1 Current Transfer Ratio (CTR) Rank (Note) (Unless otherwise specified, Ta = 25 °C)

Rank	Test Condition	Current transfer ratio Ic/I _F Min	Current transfer ratio Ic/I _F Max	Marking of Classification	Unit
GB	I _F = 5 mA, V _{CE} = 5 V	100	600	GB, GR, BL, G, G+, B	%

Note: Specify both the part number and a rank in this format when ordering.

Example: TLP185(GB-TPL,SE

For safety standard certification, however, specify the part number alone.

Example: TLP185(GB-TPL,SE → TLP185

9. Isolation Characteristics (Unless otherwise specified, Ta = 25 °C)

Characteristics	Symbol	Note	Test Condition	Min	Тур.	Max	Unit
Total capacitance (input to output)	Cs	(Note 1)	Vs = 0 V, f = 1 MHz	-	0.8	-	pF
Isolation resistance	Rs		Vs = 500 V, R.H. ≤ 60 %	10 ¹²	10 ¹⁴	1	Ω
Isolation voltage	BVs		AC, 60 s	3750	ı	1	Vrms

Note 1: This device is considered as a two-terminal device: Pins 1 and 3 are shorted together, and pins 4 and 6 are shorted together.



10. Switching Characteristics (Unless otherwise specified,Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Rise time	t _r		-	2	-	
Fall time	t _f	$V_{CC} = 10 \text{ V}, I_C = 2 \text{ mA},$	-	3	-	
Turn-on time	t _{on}	R _L = 100 Ω	-	3	-	
Turn-off time	t _{off}		-	3	-	μs
Turn-on time	t _{on}	Coo Fir 40 4	-	0.5	-	
Storage time	ts	See Fig 10.1 V_{CC} = 5 V, I_F = 16 mA, R_L = 1.9 kΩ	-	25	-	
Turn-off time	t _{off}	VCC - 5 V, IF - 10 IIIA, KL - 1.9 K22	-	40	-	

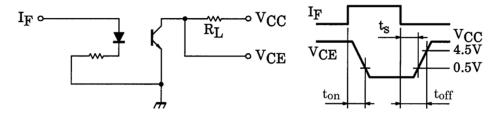
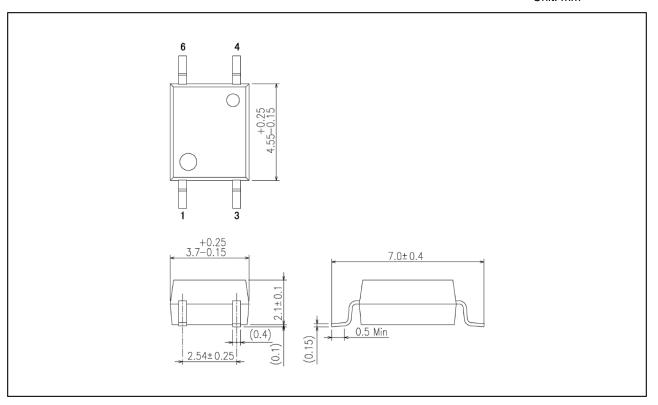


Fig. 10.1 Switching Time Test Circuit and Waveform



Package Dimensions

Unit: mm



Weight: 0.08 g (typ.)

Package Name(s)
TOSHIBA: 11-4M1S



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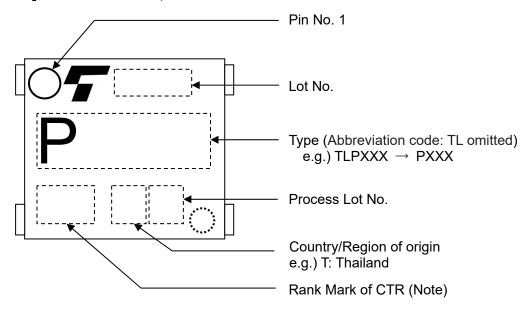
• Country / Region of origin : Diffused in Japan

Assembled in Thailand



Marking

Up to around October, 2021

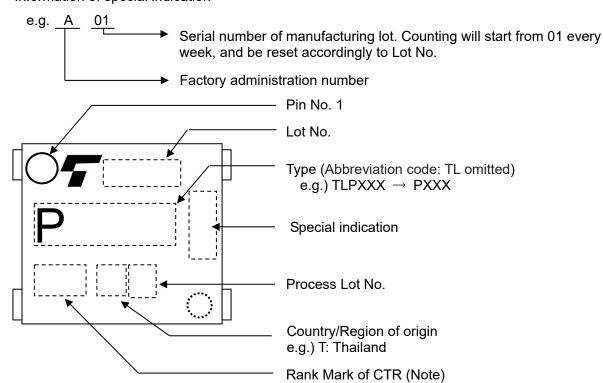


Note: Please refer to CTR rank table in the data sheet.

After October, 2021

(It is due to shift to the following one by one.)

Information of special indication



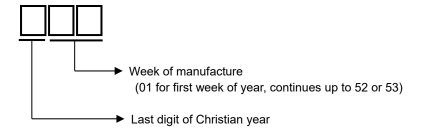
Note: Please refer to CTR rank table in the data sheet.

8 Ver.2



Explanation for Lot No. indication system

Weekly 3 digits code table



For example, "841" means that the lot is manufactured at the 41th week of ***8 year. (***8 year: A year that its last digit is 8.)

Embossed Carrier Tape Packaging specifications for 4pin SO6

Packaging of TOSHIBA semiconductor devices is compliant with IEC 60286-3.

1. Tape

1.1 Orientation of Device

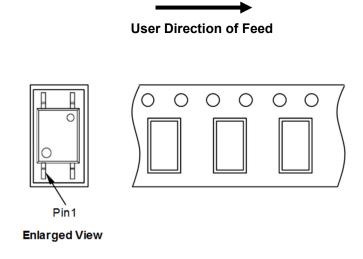


Figure 1 Orientation of Device

(The package is an example to show the orientation.)

1.2 Quantity

3000 pcs./reel

1.3 Leader and Trailer

Leader is 400mm minimum that includes 100mm minimum of empty portion. Trailer is 160mm minimum and sealed with cover tape.

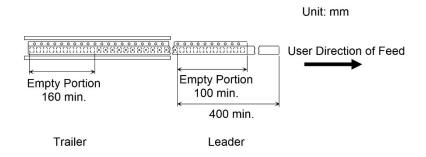


Figure 2 Leader and Trailer

1.4 Tape Dimensions

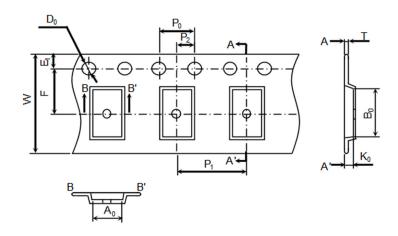


Figure 3 Tape Dimensions

(Figure 3 is an example and may differ from the actual tape. Refer to table 1 and 2 for dimensions.)

Table 1 Tape Dimensions -1

 D₀
 E₁
 P₀
 T
 P₀ Cumulative Tolerance

 1.5+0.1/0
 1.75±0.1
 4.0±0.1
 0.6max.
 ±0.2/10pitch

Table 2 Tape Dimensions -2

 F
 P1
 P2
 W
 A0
 B0
 K0

 5.5±0.05
 8.0±0.1
 2.0±0.05
 12.0
 4.0
 7.6
 2.6

1.5 Peel Strength of Cover Tape

Table 3 Peel Test Condition and Strength

Test Condition	Peel Strength
Peeling Angle: 165 - 180° vs. Embossed Carrier Tape	0.1~1.3 N
Peeling Velocity: 300mm/min.	0.1~1.3 N

2. Reel Dimensions

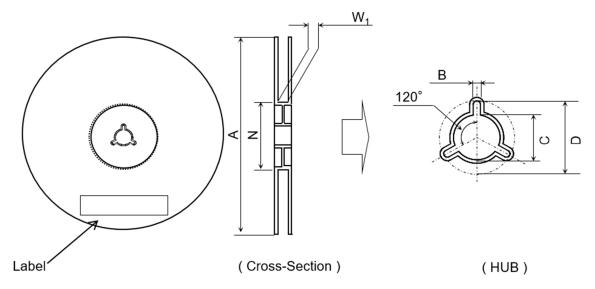


Figure 4 Reel

Table 4 Reel Dimensions

Unit: m						
Α	N	W ₁	С	D	В	
330	100	13.5	13.0±0.2	21.0±0.8	2.0±0.5	

3. Inner Carton

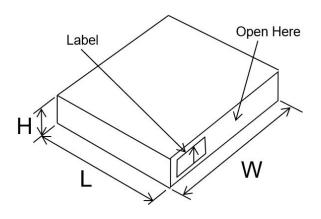


Figure 5 Inner Carton

Table 5 Inner Carton Dimensions(Outer Dimensions)

		Unit: mm
L	w	Н
350	340	30

4. Label

Figure 6 is a label affixed to a reel and a carton.

About ① to ⑨, refer to the following explanation.

Refer to Figure 4 and 5 for the label position.

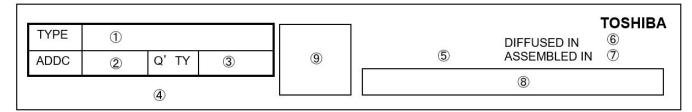


Figure 6 Label

- 1 Part Number
- 2 Additional Code
- 3 Quantity
- 4 Lot Code
- **5** Environmental Information
- 6 Country/Region of Origin(Pellet Process)
- ⑦ Country/Region of Origin(Assembly Process)
- 8 Bar Code
- Matrix Code